



Material Content Data Sheet



Sales Product Name		BFP 840FESD H6327		Issued		20. July 2018			
MA#		MA000993432							
Package		PG-TSFP-4-1		Weight*		1.87 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.001	0.04		376		
	noble metal	gold	7440-57-5	0.003	0.15		1456		
	inorganic material	silicon	7440-21-3	0.024	1.27	1.46	12696	14528	
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79		
	non noble metal	titanium	7440-32-6	0.001	0.04		394		
	non noble metal	chromium	7440-47-3	0.002	0.12		1182		
	non noble metal	copper	7440-50-8	0.734	39.24	39.41	392365	394020	
wire	noble metal	gold	7440-57-5	0.008	0.42	0.42	4182	4182	
encapsulation	organic material	carbon black	1333-86-4	0.010	0.51		5130		
	plastics	epoxy resin	-	0.206	11.03		110296		
	inorganic material	silicondioxide	60676-86-0	0.744	39.74	51.28	397578	513004	
leadfinish	non noble metal	tin	7440-31-5	0.049	2.62	2.62	26156	26156	
plating	noble metal	silver	7440-22-4	0.090	4.81	4.81	48110	48110	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com